



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Richard W. Wensel

Serial No.: 10/600,149

Filed: June 19, 2003

For: A SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK AND
TRANSFER MOLD

Confirmation No.: 6258

Examiner: Unknown

Group Art Unit: 2811

Attorney Docket No.: 2269-3061.8US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 20, 2003

Date

Signature

Deidra J. Pfeil

Name (Type/Print)

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 4 of this paper.

Amendments to the Drawings appear on page 6 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 7 of this paper.

An **Appendix** including amended drawing figures is attached following page 8 of this paper.

IN THE DRAWINGS:

The attached sheets of drawings include changes to FIGS. 2B, 3, 4A, and 4B. These sheets, which include 2B, 3, 4A, and 4B, replace the original sheets including 2A, 2B, 3, 4A, 4B, and 4C.